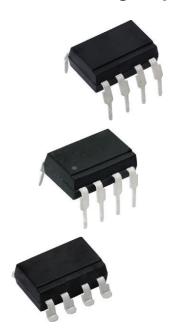
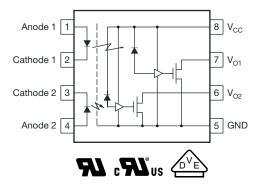


www.vishay.com

Vishay Semiconductors

High Speed Optocoupler, 10 MBd





DESCRIPTION

The VOH263A is a dual channel 10 MBd optocoupler utilizing high efficient input LEDs coupled to high speed integrated photo-detector logic gates. The detectors features an open drain outputs. The internal shield provides a guaranteed common mode transient immunity of 15 kV/µs.

FEATURES

- Common mode rejection (CMR) of min. 15 kV/ μ s
- 3.3 V / 5 V dual supply voltage
- LVTTL/LVCMOS compatibility
- Low power consumption
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





Rohs

APPLICATIONS

- Microprocessor system interface
- Ground loop elimination
- · Digital bus systems isolation
- High speed A/D and D/A conversion
- · Digital control power supply
- · Level shifting

AGENCY APPROVALS

- UL1577
- cUL
- DIN EN 60747-5-5 (VDE 0884-5), available with option 1

LINKS TO ADDITIONAL RESOURCES















ORDERING INFORMATION			
V O H	2 6 3 A	- X 0 # #	Т
PART	NUMBER	PACKAGE OPTION	TAPE AND REEL
AGENCY CERTIFIED / PACKAGE			
UL, cUL			
DIP-8		VOH263A	
DIP-8, 400 mil (option 6)		VOH263A-X006	
SMD-8 (option 7)		VOH263A-X007T	
UL, cUL, VDE (option 1)			
DIP-8	VOH263A-X001		
DIP-8, 400 mil (option 6)	VOH263A-X016		
SMD-8 (option 7)		VOH263A-X017T	

Note

· Additional options may be possible, please contact sales office

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
INPUT		·			
Input forward current		I _F	20	mA	
Reverse input voltage		V _R	5	V	
Input power dissipation		P _{diss}	40	mW	
OUTPUT					
Supply voltage		V _{CC}	7	V	
Output current		Io	50	mA	
Output voltage		V _O	7	V	
Output power dissipation		P _{diss}	85	mW	
COUPLER		·			
Storage temperature		T _{stg}	-55 to +125	°C	
Operating temperature		T _{amb}	-40 to +110	°C	
Solder reflow temperature (1)	5 s		260	°C	

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not
 implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute
 maximum ratings for extended periods of the time can adversely affect reliability
- (1) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP)

RECOMMENDED OPERATING CONDITIONS					
PARAMETER	SYMBOL	MIN.	MAX.	UNIT	
Operating temperature	T _{amb}	-40	+110	°C	
Supply valtage	V _{CC}	2.7	3.6	V	
Supply voltage	V _{CC}	4.5	5.5	V	
Input current low level	I _{FL}	0	250	μA	
Input current high level	I _{FH}	5	15	mA	
Output pull up resistor	R_L	330	4000	Ω	
Fanout ($R_L = 1 \text{ k}\Omega$)	N	-	5	TTL loads	



TRUTH TABLE (positive logic)				
LED	OUTPUT			
On	L			
Off	Н			

ELECTRICAL CHARACTERSITCS (T_{amb} = -40 °C to +110 °C, 2.7 V \leq V _{CC} \leq 3.6 V, I_F = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 3.3 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Input forward voltage	I _F = 10 mA	V_{F}	-	1.38	1.8	V
Input forward voltage temperature coefficient	I _F = 10 mA	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	I _R = 10 μA	BV_R	5	-	-	V
Input threshold current	$V_E = 2 \text{ V}, V_O = 0.6 \text{ V}, V_{CC} = 3.3 \text{ V},$ $I_{OL} \text{ (sinking)} = 13 \text{ mA}$	I _{TH}	-	2	5	mA
Input capacitance	f = 1 MHz, V _F = 0 V	C _I	-	34	-	pF
OUTPUT	•					
Low level supply current	$I_F = 10 \text{ mA}, V_{CC} = 3.3 \text{ V}$	I _{CCL}	-	6.4	10	mA
High level supply current	$I_F = 0 \text{ mA}, V_{CC} = 3.3 \text{ V}$	I _{CCH}	-	6.8	10	mA
Low level output voltage	$V_{CC} = 3.3 \text{ V}, I_F = 5 \text{ mA}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	V_{OL}	-	0.24	0.6	V
High level output current	$V_{CC} = 3.3 \text{ V}, V_E = 2 \text{ V}, V_O = 3.3 \text{ V}, I_F = 250 \mu\text{A}$	I _{OH}	-	1.3	10	μA
COUPLER						
Input to output capacitance	f = 1 MHz, T _{amb} = 25 °C	C _{IO}	-	1	-	pF

Note

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering
evaluation. Typical values are for information only and are not part of the testing requirements

ELECTRICAL CHARACTERSITCS (T_{amb} = -40 °C to +110 °C, 4.5 V \leq V _{CC} \leq 5.5 V, I_{F} = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 5.0 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Input forward voltage	I _F = 10 mA	V_{F}	-	1.38	1.8	V
Input forward voltage temperature coefficient	I _F = 10 mA	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	I _R = 10 μA	BV _R	5	-	-	V
Input threshold current	$V_E = 2 \text{ V}, V_O = 0.6 \text{ V}, V_{CC} = 5.5 \text{ V},$ $I_{OL} \text{ (sinking)} = 13 \text{ mA}$	I _{TH}	-	2.1	5	mA
Input capacitance	f = 1 MHz, V _F = 0 V	CI	-	34	-	pF
OUTPUT						
Low level supply current	$I_F = 10 \text{ mA}, V_{CC} = 5.5 \text{ V}$	I _{CCL}	-	7.2	10	mA
High level supply current	$I_F = 0 \text{ mA}, V_{CC} = 5.5 \text{ V}$	I _{CCH}	=	7.6	10	mA
Low level output voltage	$V_{CC} = 5.5 \text{ V}, I_F = 5 \text{ mA}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	V_{OL}	=	0.09	0.60	V
High level output current	$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}, I_{F} = 250 \mu\text{A}$	I _{OH}	=	1.12	10	μA
COUPLER						
Input to output capacitance	f = 1 MHz, T _{amb} = 25 °C	C _{IO}	-	4	-	pF

Note

 Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

SWITCHING CHARACTERISTICS (T_{amb} = -40 °C to +110 °C, 2.7 V \leq V _{CC} \leq 3.6 V, I_F = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 3.3 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to high output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH}	20	50	90	ns
Propagation delay time to low output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PHL}	25	44	75	ns
Pulse width distortion	$R_L = 350 \Omega$, $C_L = 15 pF$	t _{PLH} - t _{PHL}	-	10	-	ns
Propagation delay skew	$R_L = 350 \Omega$, $C_L = 15 pF$	t _{PSK}	ı	-	40	ns
Output rise time (10 % to 90 %)	$R_L = 350 \Omega, C_L = 15 pF$	t _r		2.3	-	ns
Output fall time (90 % to 10 %)	$R_L = 350 \Omega$, $C_L = 15 pF$	t _f		11	-	ns

SWITCHING CHARACTERISTICS (T_{amb} = -40 °C to +110 °C, 4.5 V \leq V _{CC} \leq 5.5 V, I_F = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 5.0 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to	$R_L = 350 \Omega$, $C_L = 15 pF$, $T_{amb} = 25 °C$	t _{PLH}	25	50	90	ns
high output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH}	-	-	100	ns
Propagation delay time to	$R_L = 350 \Omega$, $C_L = 15 pF$, $T_{amb} = 25 °C$	t _{PHL}	25	40	90	ns
low output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PHL}	-	ı	100	ns
Pulse width distortion	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH} - t _{PHL}	-	10	-	ns
Propagation delay skew	$R_L = 350 \Omega, C_L = 15 pF$	t _{PSK}	-	-	40	ns
Output rise time (10 % to 90 %)	$R_L = 350 \Omega, C_L = 15 pF$	t _r	-	11	-	ns
Output fall time (90 % to 10 %)	$R_L = 350 \Omega, C_L = 15 pF$	t _f	-	2.3	-	ns

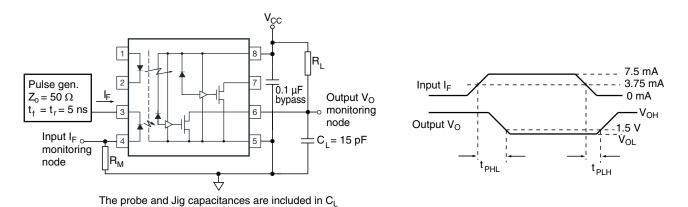


Fig. 1 - Test Circuit for t_{PLH} , t_{PHL} , t_{r} , and t_{f}



COMMON MODE TRANSIENT IMMUNITY (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	TEST CONDITION SYMBOL MIN.		TYP.	MAX.	UNIT
Logic high common mode	$V_{CC} = 3.3 \text{ V}, V_{CM} = 1000 \text{ V}, I_F = 0 \text{ mA}, $ $V_O > 2.0 \text{ V}, R_L = 350 \Omega$	CM _H	15 000	-	-	V/µs
transient immunity	$\begin{split} V_{CC} = 5 \text{ V}, & V_{CM} = 1000 \text{ V}, I_F = 0 \text{ mA}, \\ & V_O > 2.0 \text{ V}, R_L = 350 \Omega \end{split}$	CM _H	15 000	-	-	V/µs
Logic low common mode	$V_{CC} = 5 \text{ V}, V_{CM} = 1000 \text{ V}, I_F = 10 \text{ mA}, $ $V_O < 0.8 \text{ V}, R_L = 350 \Omega$	CM _L	15 000	ı	-	V/µs
transient immunity	$V_{CC} = 5 \text{ V}, \ V_{CM} = 1000 \text{ V}, \ I_F = 10 \text{ mA}, \\ V_O < 0.8 \text{ V}, \ R_L = 350 \ \Omega$	CM _L	15 000	ı	-	V/µs

Notes

• No external pull up is required for a high logic state on the enable input. If the enable pin in not used, connect it to V_{CC}

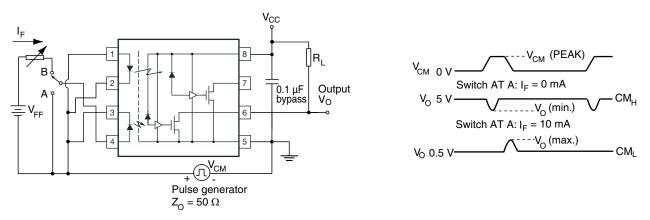


Fig. 2 - Test Circuit for Common Mode Transient Immunity

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55 / 110 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V _{ISO}	5000	V _{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V _{IOTM}	6000	V _{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V _{IORM}	630	V _{peak}
Isolation resistance	$T_{amb} = 25 ^{\circ}C, V_{IO} = 500 V$	R _{IO}	≥ 10 ¹²	Ω
Maximum output power dissipation		P _{SO}	600	mW
Maximum input current		I _{SI}	230	mA
Maximum ambient temperature (derated)		T _S	175	°C
Croopage distance	DIP-8, SMD-8		≥ 7	mm
Creepage distance	DIP-8, 400 mil		≥ 8	mm
Clearance distance	DIP-8, SMD-8		≥ 7	mm
Glearance distance	DIP-8, 400 mil		≥ 8	mm
Insulation thickness		DTI	≥ 0.4	mm

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

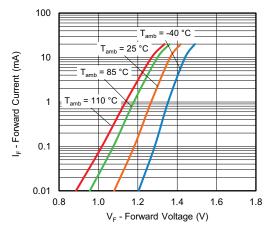


Fig. 3 - Diode Forward Current vs. Forward Voltage

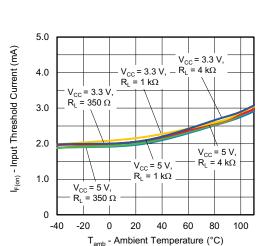


Fig. 4 - Input Threshold Current vs. Ambient Temperature

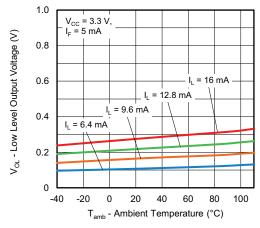


Fig. 5 - Low Level Output Voltage vs. Ambient Temperature

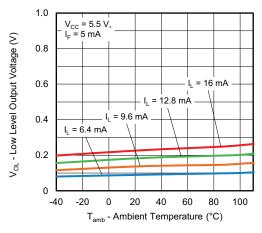


Fig. 6 - Low Level Output Voltage vs. Ambient Temperature

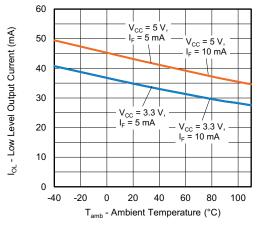


Fig. 7 - Low Level Output Current vs. Ambient Temperature

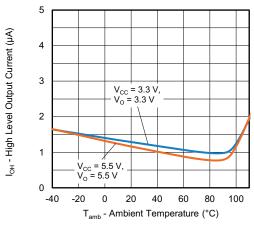


Fig. 8 - High Level Output Current vs. Ambient Temperature



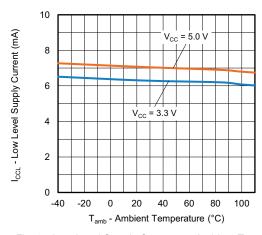


Fig. 9 - Low Level Supply Current vs. Ambient Temperature

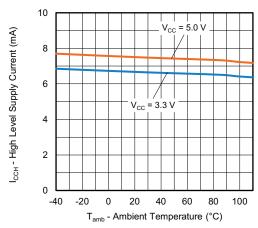


Fig. 10 - High Level Supply Current vs. Ambient Temperature

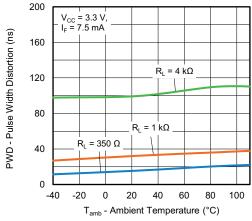


Fig. 11 - Pulse Width Distortion vs. Ambient Temperature

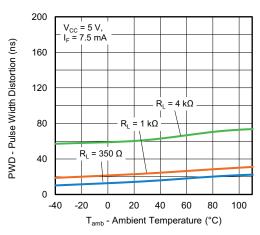


Fig. 12 - Pulse Width Distortion vs. Ambient Temperature

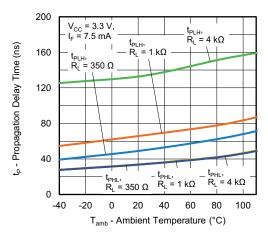


Fig. 13 - Propagation Delay Time vs. Ambient Temperature

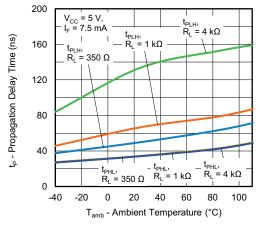
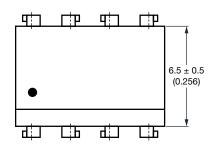
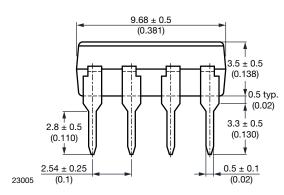


Fig. 14 - Propagation Delay Time vs. Ambient Temperature

PACKAGE DIMENSIONS (in millimeters)

DIP-8





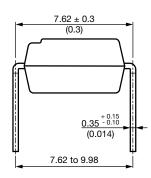
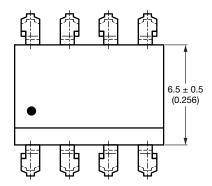


Fig. 15

DIP-8, 400 mil



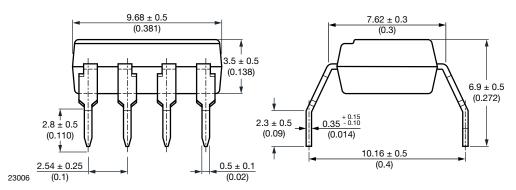
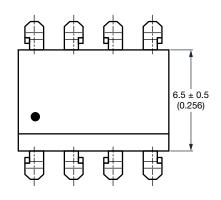
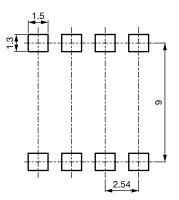
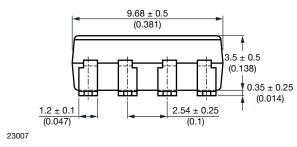


Fig. 16

SMD-8







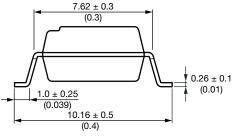


Fig. 17

PACKAGE MARKING



Fig. 18 - Example of VOH263A



Fig. 19 - Example of VOH263A-X017T

Notes

- "YWW" is the date code marking (Y = year code, WW = week code)
- VDE logo is only marked on VDE option parts
- Tape and reel suffix (T) is not part of the package marking

PACKAGING INFORMATION (in millimeters)

DEVICES PER TUBES					
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX		
DIP-8	50	40	2000		
DIP-8, 400 mil	40	30	1200		

SMD-8 Tape

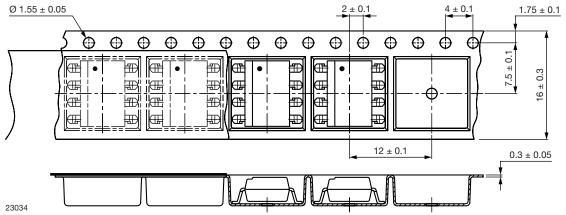


Fig. 20 - Tape and Reel Packaging (1000 pieces on reel)

Reel

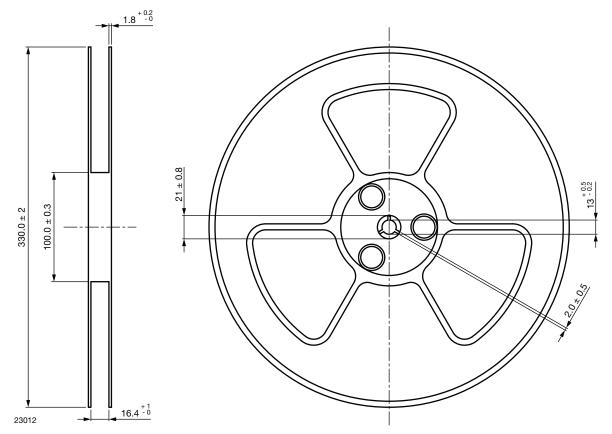


Fig. 21 - Tape and Reel Shipping Medium

SOLDER PROFILES

IR Reflow Soldering (JEDEC® J-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

PROFILE ITEM	CONDITIONS
Preheat	
- Temperature minimum (T _{S min.})	150 °C
- Temperature maximum (T _{S max.})	200 °C
- Time (min. to max.) (t _S)	90 s ± 30 s
Soldering zone	
- Temperature (T _L)	217 °C
- Time (t _L)	60 s
Peak temperature (T _p)	260 °C
Ramp-up rate	3 °C/s max.
Ramp-down rate	3 °C/s to 6 °C/s

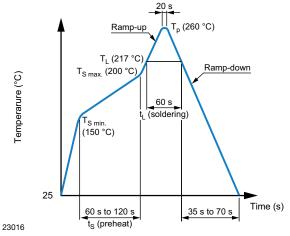


Fig. 22

Wave Soldering (JEDEC JESD22-A111 compliant)

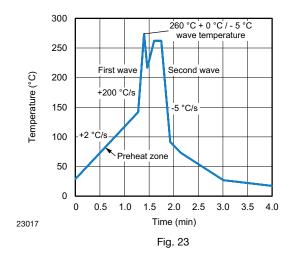
One time soldering is recommended within the condition of temperature.

Temperature: 260 °C + 0 °C / - 5 °C

Time: 10 s

Preheat temperature: 25 °C to 140 °C

Preheat time: 30 s to 80 s



Hand Soldering by Soldering Iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380 °C + 0 °C / - 5 °C

Time: 3 s max.

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2 Floor life: unlimited

Conditions: $T_{amb} < 30$ °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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Vishay

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